

cont
A3

connecting the conductive pattern to the via conductor.

6. (Amended) The method of claim 4, further comprising the steps of:

A4

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive pattern to the via-conductor.

9. (Amended) The method of claim 7, further comprising the steps of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive patterns to the via-conductor.

10. (Amended) The method of claim 7, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered substrate; and

connecting the conductive pattern to the via-conductor.

13. (Amended) The method of claim 11, further comprising the step of:

forming a via-conductor through forming a through-hole in the un-sintered green sheet;

and

connecting the conductive patterns to the via-hole conductor.

14. (Amended) The method of claim 11, further comprising the steps of:

forming a via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting the conductive pattern to the via-conductor.

17. (Amended) The method of claim 15, wherein the first intaglio and the second

intaglio are identical to each other.

18. (Amended) The method of claim 15, further comprising the steps of:

forming a first via-conductor through forming a through-hole in the un-sintered green sheet; and

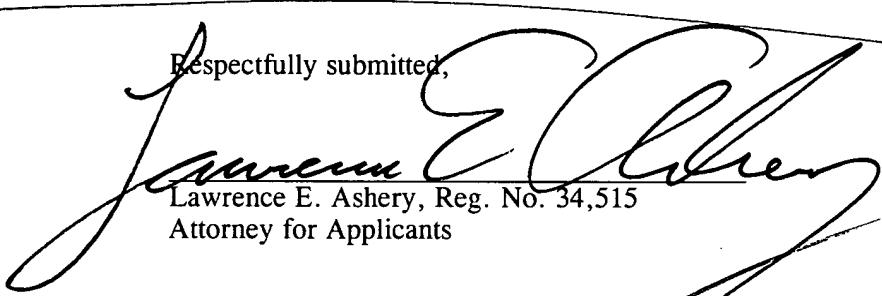
connecting at least one of the first and second conductive patterns to the first via-conductor.

19. (Amended) The method of claim 15, further comprising the steps of:

forming a second via-conductor through forming a through-hole in the sintered ceramic substrate; and

connecting at least one of said first and second conductive patterns to the second via-conductor.

Respectfully submitted,


Lawrence E. Ashery, Reg. No. 34,515

Attorney for Applicants

LEA/fp

Enclosure: Version With Markings Showing Changes Made

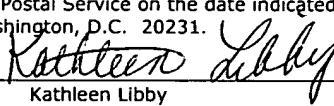
Dated: February 7, 2002

Suite 301, One Westlakes, Berwyn
P.O. Box 980
Valley Forge, PA 19482-0980
(610) 407-0700

The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. **18-0350** of any fees associated with this communication.

EXPRESS MAIL Mailing Label Number: **EL 743 541 775 US**
Date of Deposit: **February 7, 2002**

I hereby certify that this paper and fee are being deposited, under 37 C.F.R. § 1.10 and with sufficient postage, using the "Express Mail Post Office to Addressee" service of the United States Postal Service on the date indicated above and that the deposit is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


Kathleen Libby

Kathleen Libby